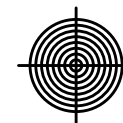
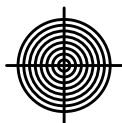
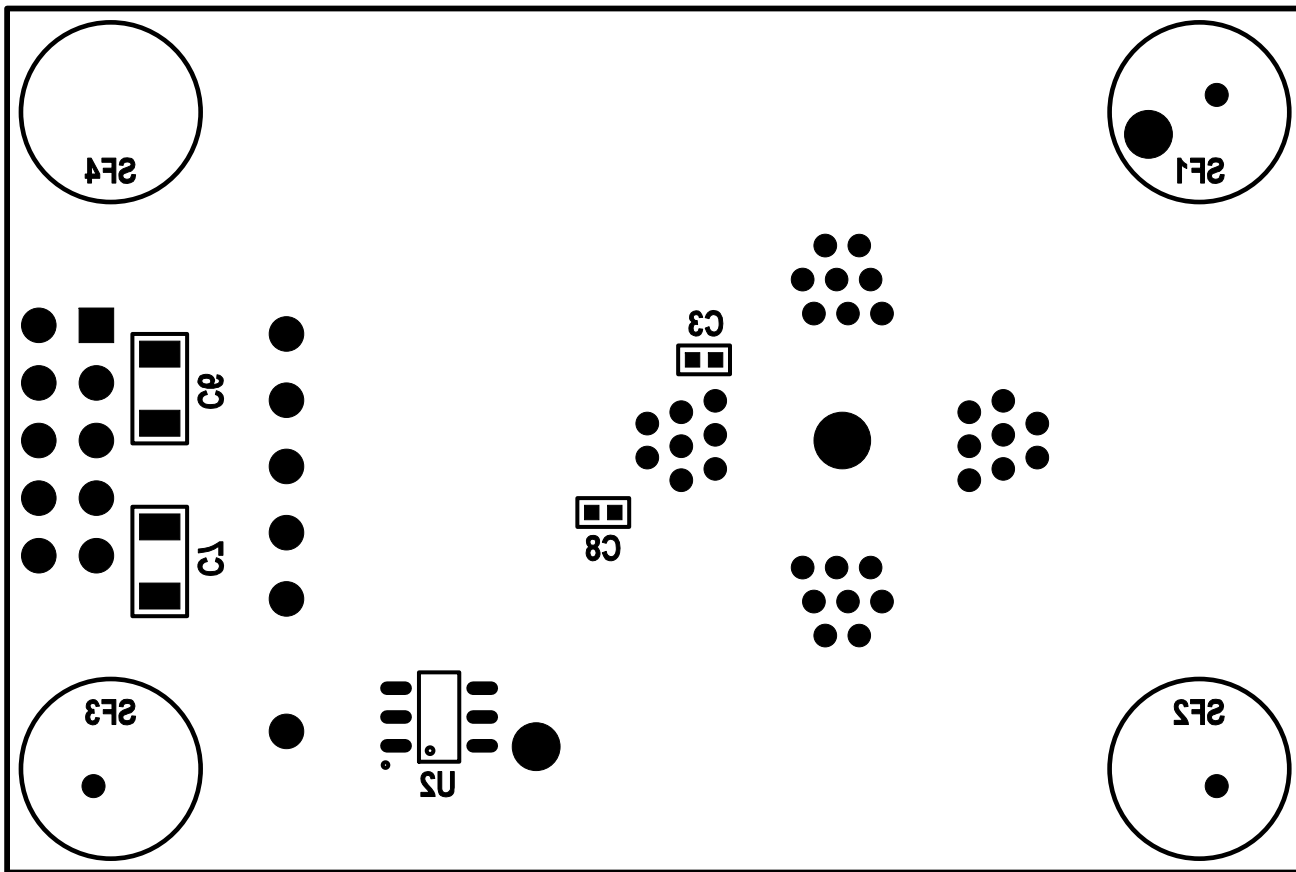
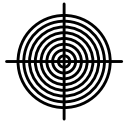
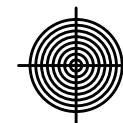
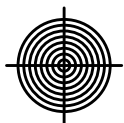


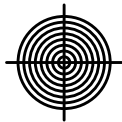
PRIMARY SILKSCREEN





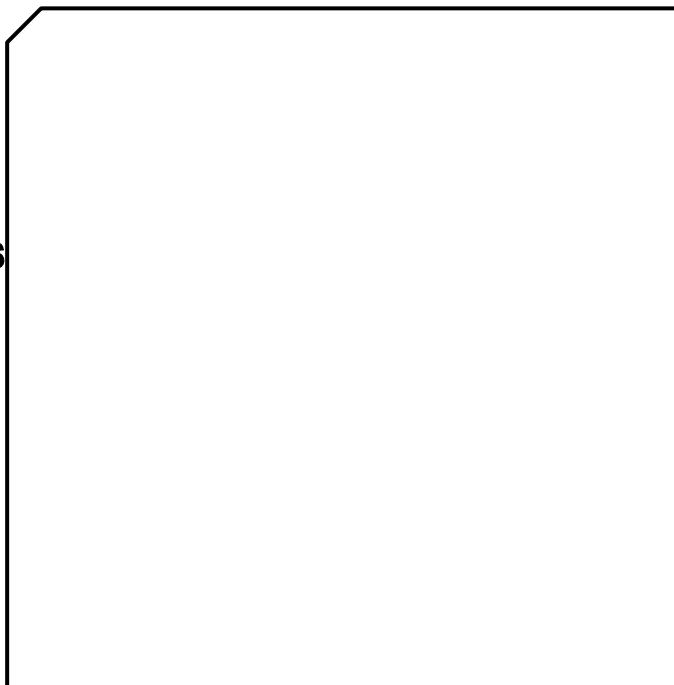
SECONDARY SILKSCREEN





SiLabs® 32-Pin Clock Gen SKT REV 1.0

U1



X1

GND

SCLK

SDA

TP2
VDDA_VDDS

TP8
SCLK

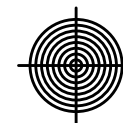
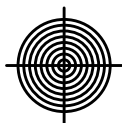
TP9
SDA

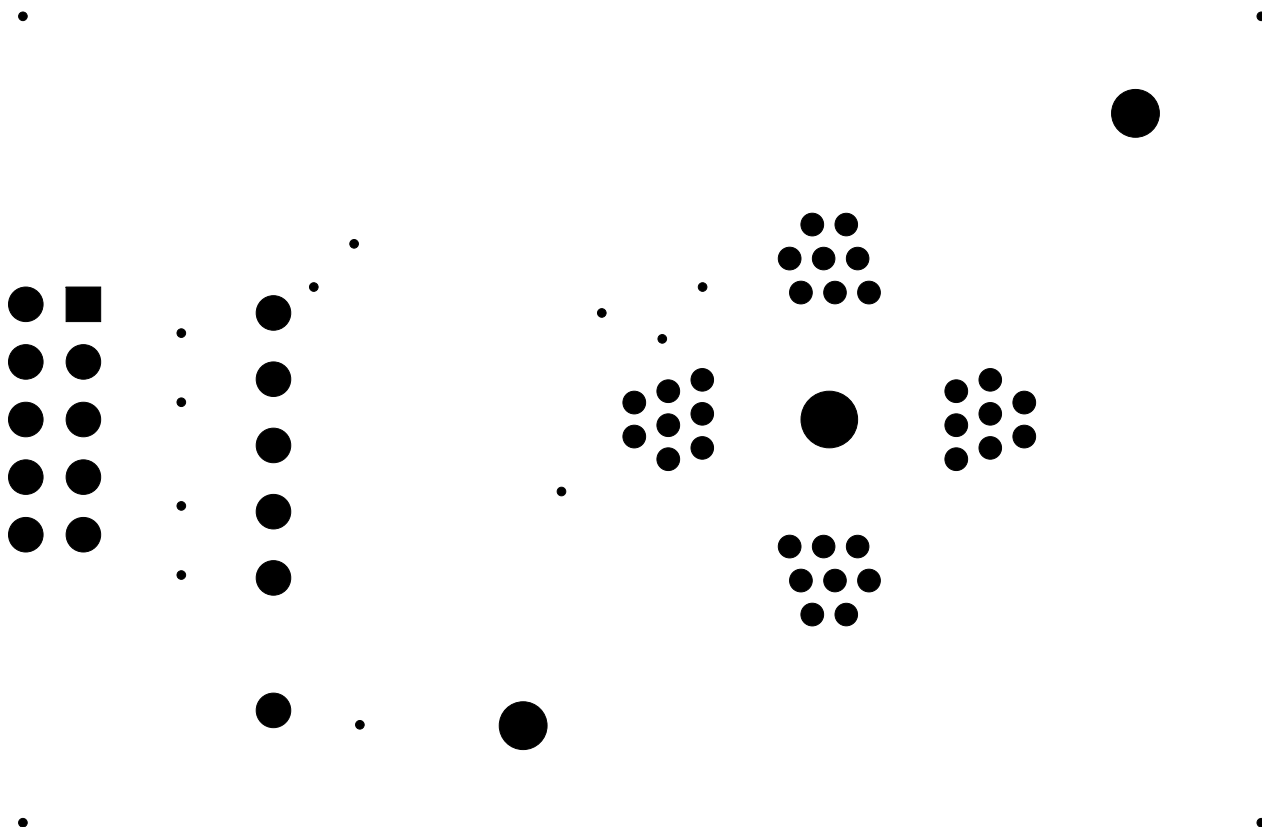
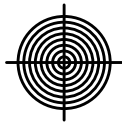
TP1
VDD

TP7
GND

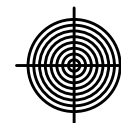
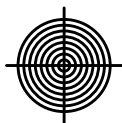
TP6
ID

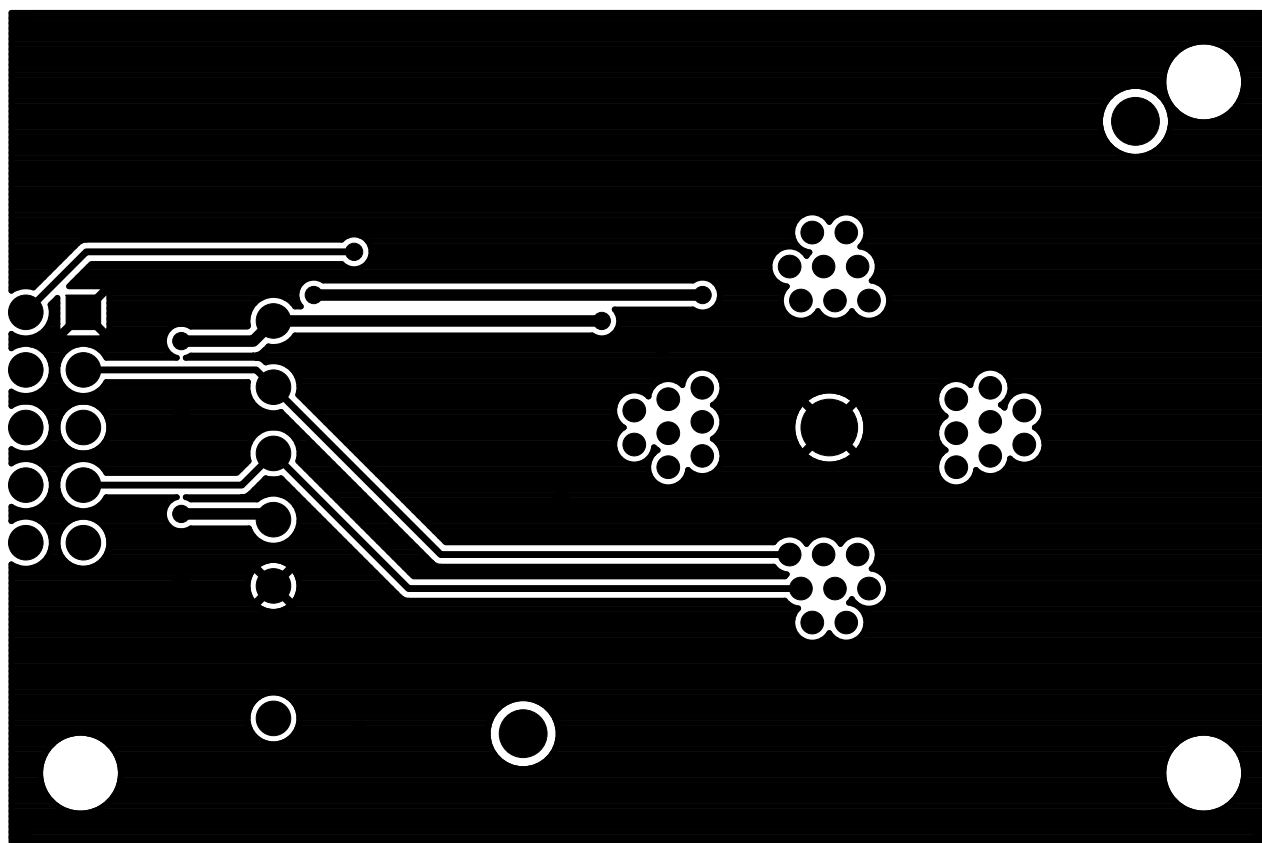
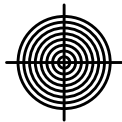
PRIMARY SILKSCREEN



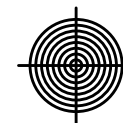
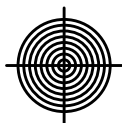


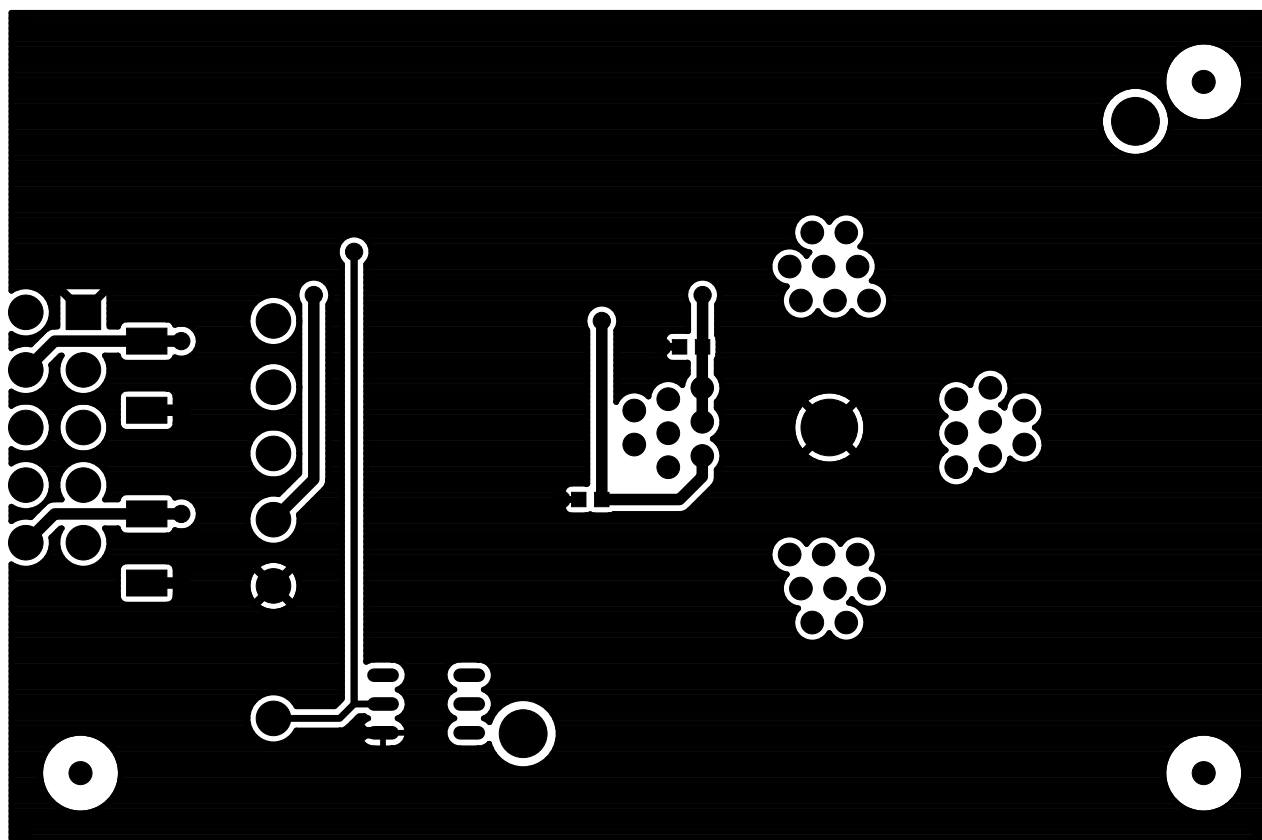
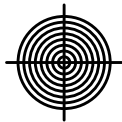
PRIMARY SOLDER MASK



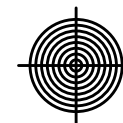
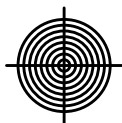


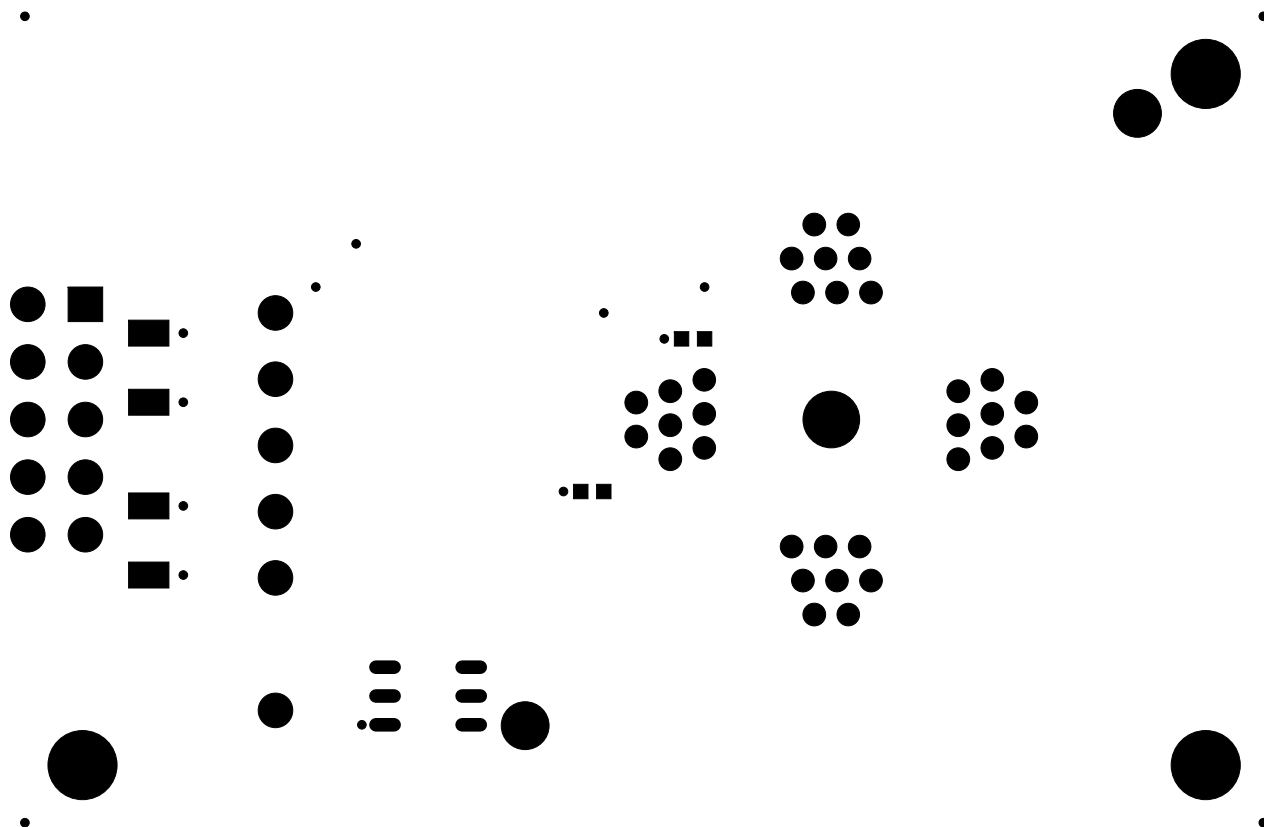
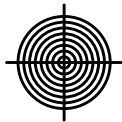
PRIMARY SIDE



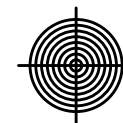
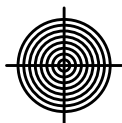


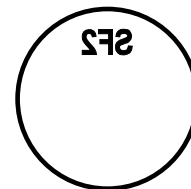
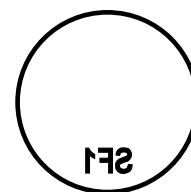
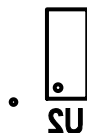
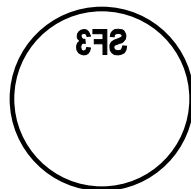
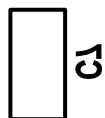
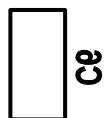
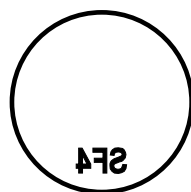
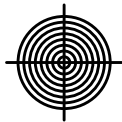
BOTTOM SIDE



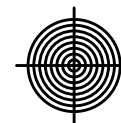
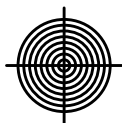


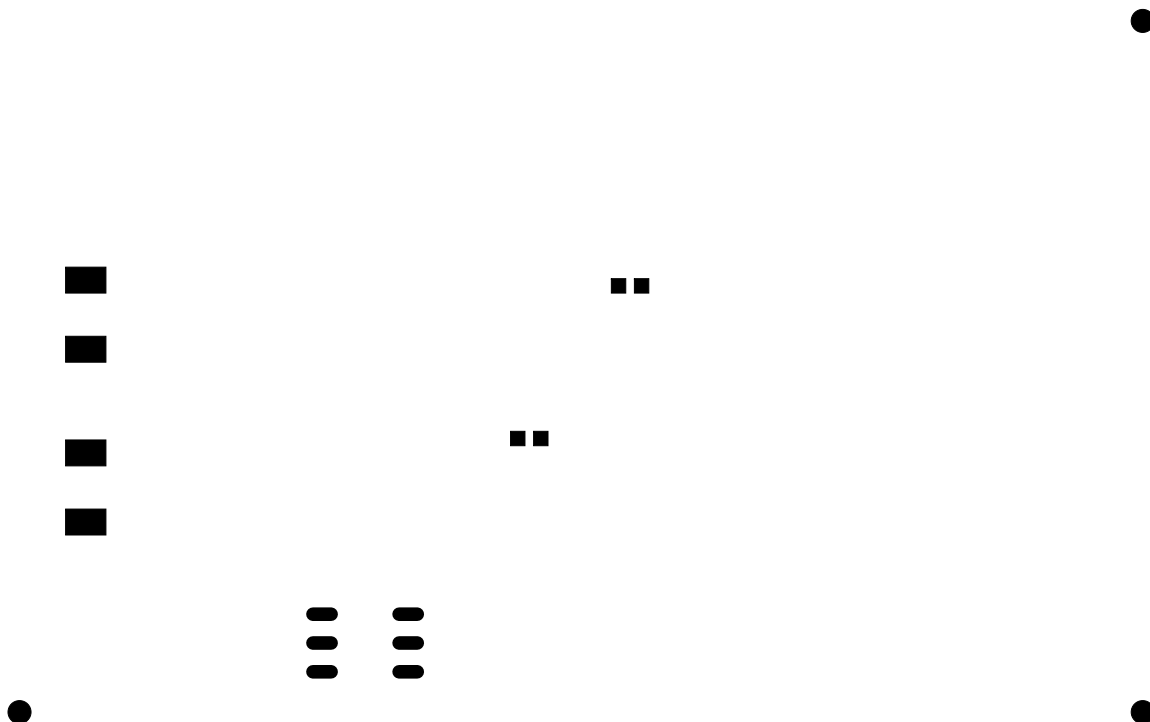
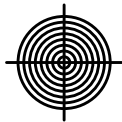
SECONDARY SOLDER MASK



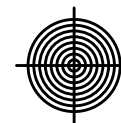
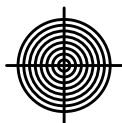


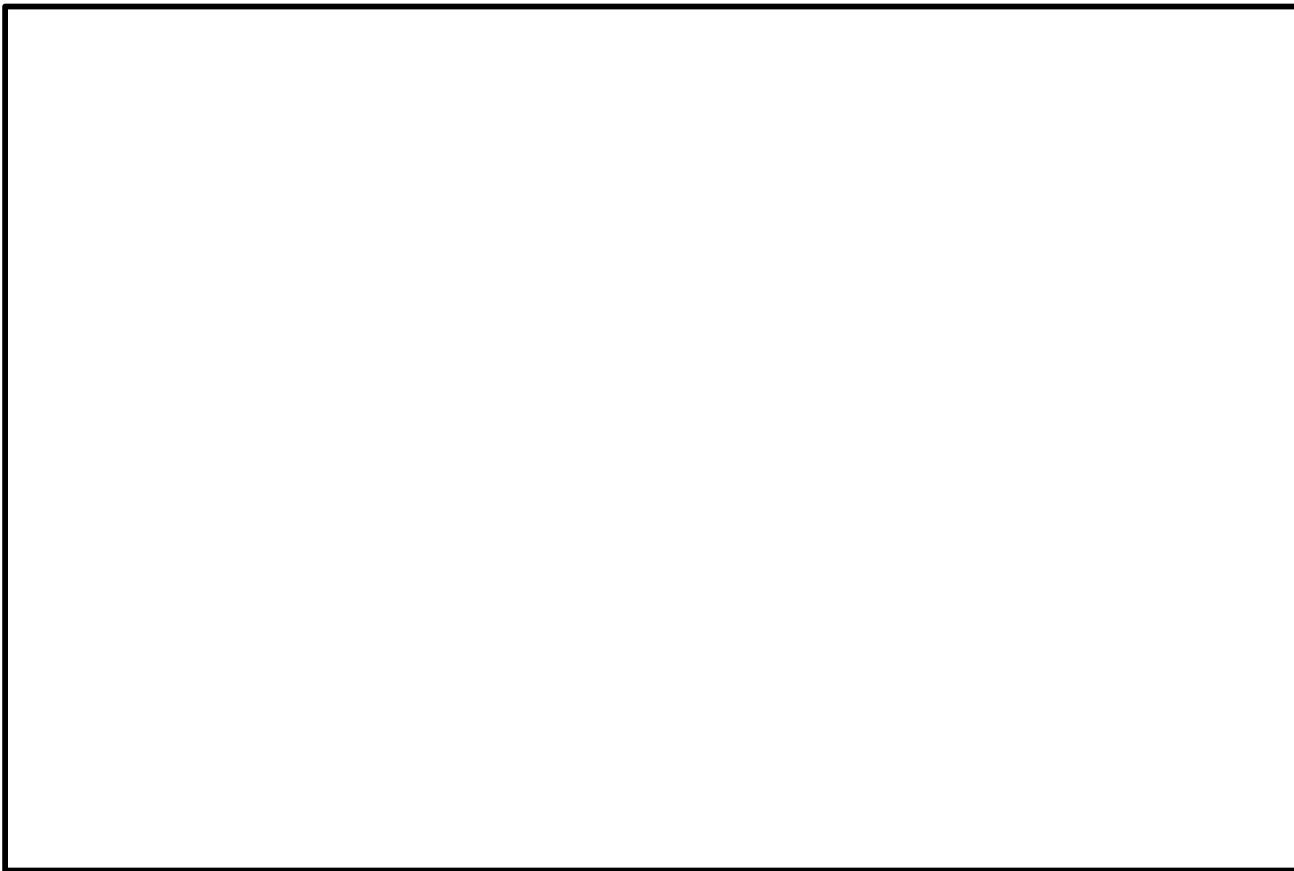
SECONDARY SILKSCREEN

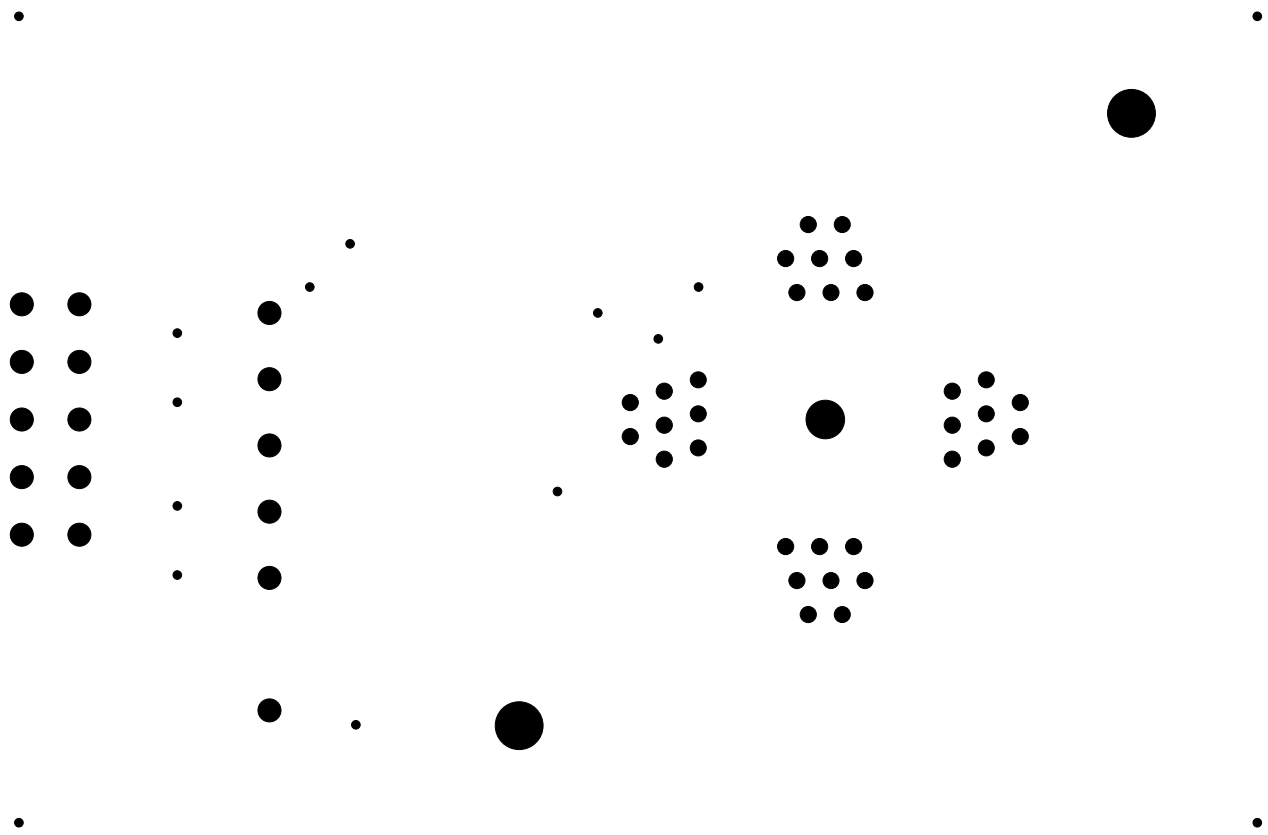




SECONDARY SOLDER PASTE

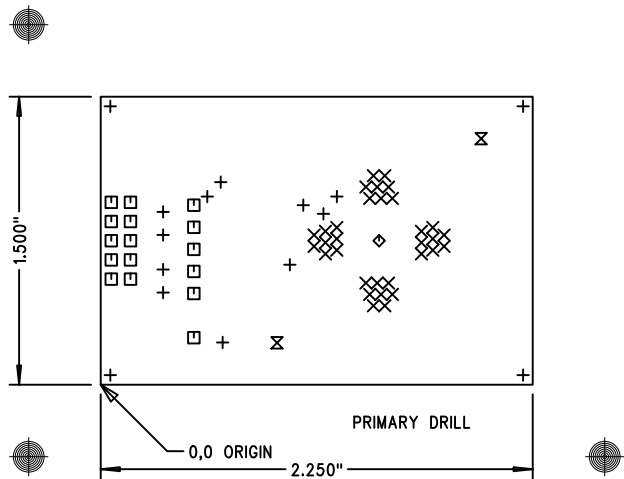






NOTES : UNLESS OTHERWISE SPECIFIED


1. MANUFACTURE IN ACCORDANCE WITH IPC-6012, TYPE 3, CLASS 2.
2. END PRODUCT FEATURES SHALL NOT VARY MORE THAN 20% FROM ARTWORK ORIGINALS.
3. LAMINATE AND PREPREG SHALL BE AS PER IPC-4101/26,83,98 WITH A DECOMPOSITION TEMPERATURE $\geq 345^{\circ}\text{C}$, COLOR, NATURAL.
4. COPPER WEIGHT SHALL BE 1.0 OZ./SQ. FT. BEFORE PLATING.
5. ALL PLATED THROUGH HOLES SHALL HAVE A MINIMUM OF 0.001" COPPER.
6. DRILL HOLE TOLERANCE AFTER PLATING SHALL BE ± 0.003 ".
7. MINIMUM ANNULAR RING SHALL BE 0.001".
8. MINIMUM ANNULAR RING AT EMERGENT CONDUCTORS SHALL BE 0.003".
9. FINAL PCB THICKNESS SHALL BE 0.062" $\pm 10\%$.
10. WARP/TWIST SHALL NOT EXCEED 1.0%
11. FINISH SHALL BE LPI, BLUE S.M.O.B.C., BALANCE ENIG.
12. SILKSCREEN WITH NONCONDUCTIVE WHITE EPOXY INK.
13. REFERENCE ADDITIONAL FAB NOTES IN FILE README.TXT

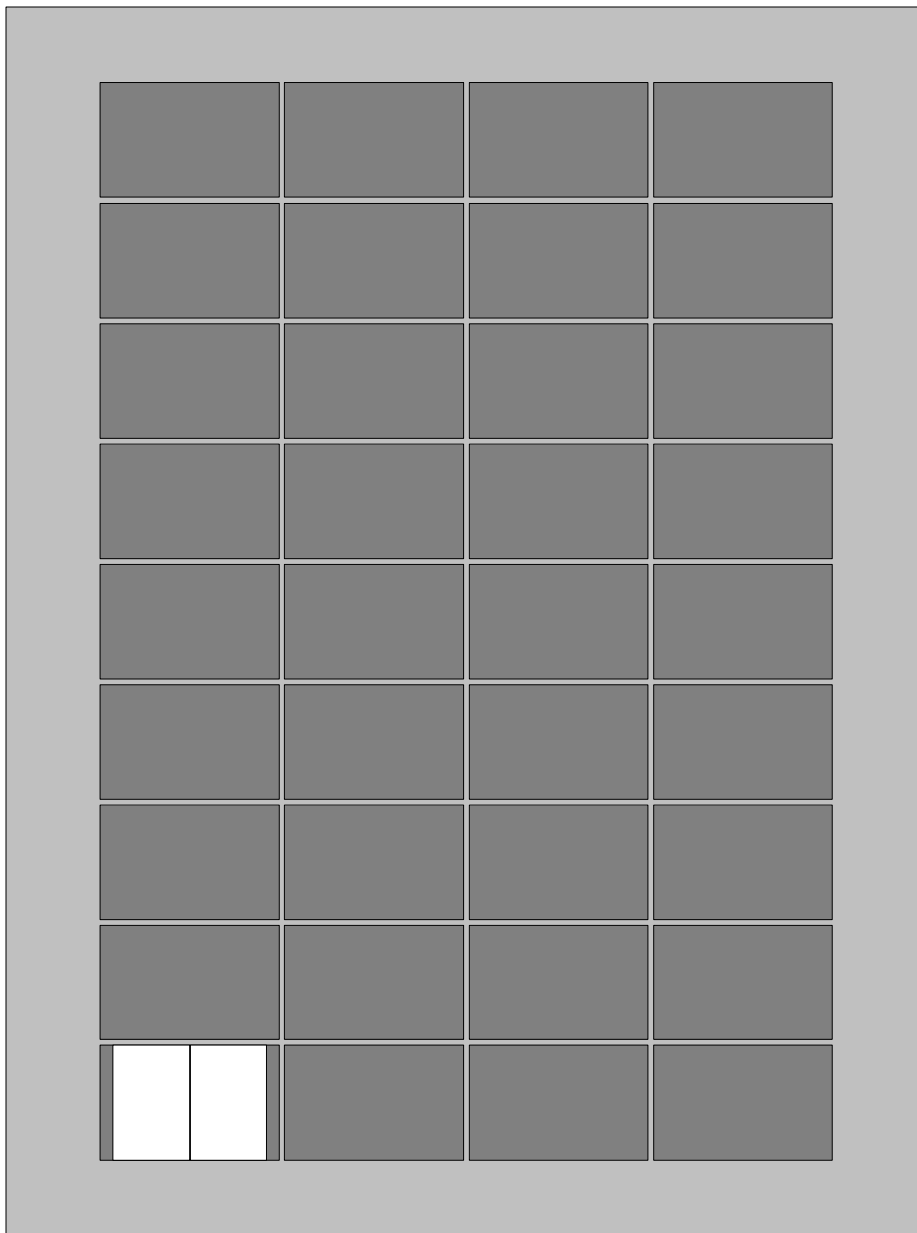


LAYER STACKUP	FILE NAMES
PRIMARY SILKSCREEN	5332-32SKT_PSS.PHO
PRIMARY SOLDERMASK	5332-32SKT_PSM.PHO
PRIMARY SIDE	5332-32SKT_PRI.PHO
SECONDARY SIDE	5332-32SKT_SEC.PHO
SECONDARY SOLDERMASK	5332-32SKT_SSM.PHO
SECONDARY SILKSCREEN	5332-32SKT_SSS.PHO

SCALE: NONE

SIZE	QTY	SYM	PLT	TOOL	TOL
0.015	15	+	P	1	+0/-0.015
0.028	32	X	P	2	+/-0.003
0.040	16	□	P	3	+/-0.003
0.067	1	◇	P	4	+/-0.003
0.083	2	⊗	N	5	+/-0.003

UNLESS OTHERWISE SPECIFIED			THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION AND SHALL NOT BE DUPLICATED OR USED FOR ANY PURPOSE OTHER THAN THAT FOR WHICH PROVIDED OR DISCLOSED IN WHOLE OR IN PART, WITHOUT THE WRITTEN CONSENT OF SILICON LABORATORIES, INC..			COMPANY:  400 W Cesar Chavez AUSTIN, TX 78701 (512)416-8500 www.silabs.com			
DIMENSIONS ARE IN INCHES AND APPLY AFTER FINISH DIMENSIONS IN BRACKETS [] ARE IN MILLIMETERS INTERPRET DRAWING PER MIL-D-1000			DESIGN TT 08JUNE2017 LAYOUT AA 08JUNE2017			NAME: Si5332-32SKT			REV : 1.0
TOLERANCES HOLE TOLERANCES PER 78027						PART NUMBER:			
DECIMALS .XX +/- .XXX +/-	ANGLES +/-	SURFACES MICROINCHES	PART TO BE FREE OF BURRS			SCALE 1:1			FABRICATION DRAWING
BREAK EDGES MAX	BEND RADIUS MAX	BEND RELIEF MAX	DO NOT SCALE DRAWING			SHEET 1 OF 1			



Si5332-32SKT Rev1.0

Size:

Panel: 18.0 x 24.0

Array: 3.5 x 2.25

Part: 1.5 x 2.25

Panel Yield:

36 Arrays of 2 Parts

72 Parts Total

65.6% Material Utilization

Matrix:

On Panel: 4 x 9, Origin: X1.85 Y1.475

On Array: 2 x 1

Spacing:

On Panel: 0.1 x 0.1

On Array: 0.0 x 0.0

Panel Borders:

Left: 1.85 Right: 1.85

Top: 1.475 Bottom: 1.475

Array Borders:

Left: 0.25 Right: 0.25

Top: 0.0 Bottom: 0.0

Notes:

Please add 4, 0.125" NP tooling holes located 0.125" from tab corners and 3, 40/120 fiduials to each side of array located 0.25" from tooling holes.